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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	·
Peripherals	Brown-out Detect/Reset, POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	128 x 8
RAM Size	96 x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 5.5V
Data Converters	·
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16ce623-20-ss

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

5.2 PORTB and TRISB Registers

PORTB is an 8-bit wide, bi-directional port. The corresponding data direction register is TRISB. A '1' in the TRISB register puts the corresponding output driver in a high impedance mode. A '0' in the TRISB register puts the contents of the output latch on the selected pin(s).

Reading PORTB register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Each of the PORTB pins has a weak internal pull-up ($\approx 200 \ \mu A$ typical). A single control bit can turn on all the pull-ups. This is done by clearing the \overline{RBPU} (OPTION<7>) bit. The weak pull-up is automatically turned off when the port pin is configured as an output. The pull-ups are disabled on Power-on Reset.

Four of PORTB's pins, RB<7:4>, have an interrupt on change feature. Only pins configured as inputs can cause this interrupt to occur (i.e., any RB<7:4> pin configured as an output is excluded from the interrupt on change comparison). The input pins of RB<7:4> are compared with the old value latched on the last read of PORTB. The "mismatch" outputs of RB<7:4> are OR'ed together to generate the RBIF interrupt (flag latched in INTCON<0>).





This interrupt can wake the device from SLEEP. The user, in the interrupt service routine, can clear the interrupt in the following manner:

- a) Any read or write of PORTB. This will end the mismatch condition.
- b) Clear flag bit RBIF.

A mismatch condition will continue to set flag bit RBIF. Reading PORTB will end the mismatch condition and allow flag bit RBIF to be cleared.

This interrupt on mismatch feature, together with software configurable pull-ups on these four pins allow easy interface to a key pad and make it possible for wake-up on key-depression. (See AN552, "Implementing Wake-Up on Key Strokes".)

Note:	If a change on the I/O pin should occur
	when the read operation is being executed
	(start of the Q2 cycle), then the RBIF inter-
	rupt flag may not get set.

The interrupt on change feature is recommended for wake-up on key depression operation and operations where PORTB is only used for the interrupt on change feature. Polling of PORTB is not recommended while using the interrupt on change feature.





5.3 <u>I/O Programming Considerations</u>

5.3.1 BI-DIRECTIONAL I/O PORTS

Any instruction which writes, operates internally as a read followed by a write operation. The BCF and BSF instructions, for example, read the register into the CPU, execute the bit operation and write the result back to the register. Caution must be used when these instructions are applied to a port with both inputs and outputs defined. For example, a BSF operation on bit5 of PORTB will cause all eight bits of PORTB to be read into the CPU. Then the BSF operation takes place on bit5 and PORTB is written to the output latches. If another bit of PORTB is used as a bidirectional I/O pin (i.e., bit0) and it is defined as an input at this time, the input signal present on the pin itself would be read into the CPU and re-written to the data latch of this particular pin, overwriting the previous content. As long as the pin stays in the input mode, no problem occurs. However, if bit0 is switched into output mode later on, the content of the data latch may now be unknown.

Reading the port register, reads the values of the port pins. Writing to the port register writes the value to the port latch. When using read modify write instructions (i.e., BCF, BSF, etc.) on a port, the value of the port pins is read, the desired operation is done to this value, and this value is then written to the port latch.

Example 5-2 shows the effect of two sequential read-modify-write instructions (i.e., ${\tt BCF}\,,\,\,{\tt BSF},\, etc.)$ on an I/O port.

A pin actively outputting a Low or High should not be driven from external devices at the same time in order to change the level on this pin ("wired-or", "wired-and"). The resulting high output currents may damage the chip.

EXAMPLE 5-2: READ-MODIFY-WRITE INSTRUCTIONS ON AN I/O PORT

; Initial PORT settings: PORTB<7:4> Inputs ; PORTB<3:0> Outputs ; ; PORTB<7:6> have external pull-up and are not ; connected to other circuitry ; PORT latch PORT pins ; ; BCF PORTB. 7 ; 01pp pppp 11pp pppp BCF PORTB, 6 ; 10pp pppp 11pp pppp BSF STATUS, RPO ; BCF TRISB, 7 ; 10pp pppp 11pp pppp BCF TRISB, 6 ; 10pp pppp 10pp pppp ; ; Note that the user may have expected the pin

; values to be 00pp pppp. The 2nd BCF caused ; RB7 to be latched as the pin value (High).

5.3.2 SUCCESSIVE OPERATIONS ON I/O PORTS

The actual write to an I/O port happens at the end of an instruction cycle, whereas for reading, the data must be valid at the beginning of the instruction cycle (Figure 5-7). Therefore, care must be exercised if a write followed by a read operation is carried out on the same I/O port. The sequence of instructions should allow the pin voltage to stabilize (load dependent) before the next instruction causes that file to be read into the CPU. Otherwise, the previous state of that pin may be read into the CPU rather than the new state. When in doubt, it is better to separate these instructions with an NOP or another instruction not accessing this I/O port.



FIGURE 5-7: SUCCESSIVE I/O OPERATION





FIGURE 6-8: RANDOM READ

BUS ACTIVITY

. .

A C K

DATAn



DATAn + 1

DATAn + 2

N O

A C K

DATAn + X

PIC16CE62X





FIGURE 7-4: TIMER0 INTERRUPT TIMING



8.1 <u>Comparator Configuration</u>

There are eight modes of operation for the comparators. The CMCON register is used to select the mode. Figure 8-1 shows the eight possible modes. The TRISA register controls the data direction of the comparator pins for each mode. If the comparator

mode is changed, the comparator output level may not be valid for the specified mode change delay shown in Table 13-1.

Note: Comparator interrupts should be disabled during a comparator mode change, otherwise a false interrupt may occur.



FIGURE 8-1: COMPARATOR I/O OPERATING MODES

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on: POR	Value on All Other Resets
1Fh	CMCON	C2OUT	C1OUT	_	—	CIS	CM2	CM1	CM0	00 0000	00 0000
9Fh	VRCON	VREN	VROE	VRR	—	VR3	VR2	VR1	VR0	000- 0000	000- 0000
0Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	CMIF	_	—	—	_	—	—	-0	-0
8Ch	PIE1	—	CMIE	_	—	—	_	—	—	-0	-0
85h	TRISA		_	_	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	1 1111	1 1111
Logondi											

TABLE 8-1: REGISTERS ASSOCIATED WITH COMPARATOR MODULE

Legend: - = Unimplemented, read as "0", x = Unknown, u = unchanged

10.2.3 EXTERNAL CRYSTAL OSCILLATOR CIRCUIT

Either a prepackaged oscillator can be used or a simple oscillator circuit with TTL gates can be built. Prepackaged oscillators provide a wide operating range and better stability. A well-designed crystal oscillator will provide good performance with TTL gates. Two types of crystal oscillator circuits can be used; one with series resonance or one with parallel resonance.

Figure 10-3 shows implementation of a parallel resonant oscillator circuit. The circuit is designed to use the fundamental frequency of the crystal. The 74AS04 inverter performs the 180° phase shift that a parallel oscillator requires. The 4.7 k Ω resistor provides the negative feedback for stability. The 10 k Ω potentiometers bias the 74AS04 in the linear region. This could be used for external oscillator designs.

FIGURE 10-3: EXTERNAL PARALLEL RESONANT CRYSTAL OSCILLATOR CIRCUIT



Figure 10-4 shows a series resonant oscillator circuit. This circuit is also designed to use the fundamental frequency of the crystal. The inverter performs a 180° phase shift in a series resonant oscillator circuit. The 330 k Ω resistors provide the negative feedback to bias the inverters in their linear region.

FIGURE 10-4: EXTERNAL SERIES RESONANT CRYSTAL OSCILLATOR CIRCUIT



10.2.4 RC OSCILLATOR

For timing insensitive applications the "RC" device option offers additional cost savings. The RC oscillator frequency is a function of the supply voltage, the resistor (Rext) and capacitor (Cext) values, and the operating temperature. In addition to this, the oscillator frequency will vary from unit to unit due to normal process parameter variation. Furthermore, the difference in lead frame capacitance between package types will also affect the oscillation frequency, especially for low Cext values. The user also needs to take into account variation due to tolerance of external R and C components used. Figure 10-5 shows how the R/C combination is connected to the PIC16CE62X. For Rext values below 2.2 k Ω , the oscillator operation may become unstable, or stop completely. For very high Rext values (i.e., 1 M Ω), the oscillator becomes sensitive to noise, humidity and leakage. Thus, we recommend to keep Rext between 3 k Ω and 100 k Ω .

Although the oscillator will operate with no external capacitor (Cext = 0 pF), we recommend using values above 20 pF for noise and stability reasons. With no or small external capacitance, the oscillation frequency can vary dramatically due to changes in external capacitances, such as PCB trace capacitance or package lead frame capacitance.

See Section 14.0 for RC frequency variation from part to part due to normal process variation. The variation is larger for larger R (since leakage current variation will affect RC frequency more for large R) and for smaller C (since variation of input capacitance will affect RC frequency more).

See Section 14.0 for variation of oscillator frequency due to VDD for given Rext/Cext values, as well as frequency variation due to operating temperature for given R, C, and VDD values.

The oscillator frequency, divided by 4, is available on the OSC2/CLKOUT pin and can be used for test purposes or to synchronize other logic (Figure 3-2 for waveform).

FIGURE 10-5: RC OSCILLATOR MODE



DS40182D-page 52

10.3 <u>Reset</u>

The PIC16CE62X differentiates between various kinds of reset:

- a) Power-on reset (POR)
- b) MCLR reset during normal operation
- c) MCLR reset during SLEEP
- d) WDT reset (normal operation)
- e) WDT wake-up (SLEEP)
- f) Brown-out Reset (BOD)

Some registers are not affected in any reset condition. Their status is unknown on POR and unchanged in any other reset. Most other registers are reset to a "reset state" on Power-on reset, MCLR reset, WDT reset and MCLR reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. TO and PD bits are set or cleared differently in different reset situations as indicated in Table 10-4. These bits are used in software to determine the nature of the reset. See Table 10-6 for a full description of reset states of all registers.

A simplified block diagram of the on-chip reset circuit is shown in Figure 10-6.

The $\overline{\text{MCLR}}$ reset path has a noise filter to detect and ignore small pulses. See Table 13-5 for pulse width specification.



FIGURE 10-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT

10.4.5 TIME-OUT SEQUENCE

On power-up, the time-out sequence is as follows: First PWRT time-out is invoked after POR has expired, then OST is activated. The total time-out will vary based on oscillator configuration and <u>PWRTE</u> bit status. For example, in RC mode with <u>PWRTE</u> bit erased (PWRT disabled), there will be no time-out at all. Figure 10-8, Figure 10-9 and Figure 10-10 depict time-out sequences.

Since the time-outs occur from the POR pulse, if $\overline{\text{MCLR}}$ is kept low long enough, the time-outs will expire. Then bringing $\overline{\text{MCLR}}$ high will begin execution immediately (see Figure 10-9). This is useful for testing purposes or to synchronize more than one $\text{PIC}^{\textcircled{B}}$ device operating in parallel.

Table 10-5 shows the reset conditions for some special registers, while Table 10-6 shows the reset conditions for all the registers.

10.4.6 POWER CONTROL (PCON)/STATUS REGISTER

The power control/status register, PCON (address 8Eh) has two bits.

Bit0 is $\overline{\text{BOR}}$ (Brown-out). $\overline{\text{BOR}}$ is unknown on power-on-reset. It must then be set by the user and checked on subsequent resets to see if $\overline{\text{BOR}} = 0$ indicating that a brown-out has occurred. The $\overline{\text{BOR}}$ status bit is a don't care and is not necessarily predictable if the brown-out circuit is disabled (by setting BODEN bit = 0 in the Configuration word).

Bit1 is POR (Power-on-reset). It is a '0' on power-on-reset and unaffected otherwise. The user must write a '1' to this bit following a power-on-reset. On a subsequent reset, if POR is '0', it will indicate that a power-on-reset must have occurred (VDD may have gone too low).

Oscillator Configuration	Powe	er-up	Brown-out Beset	Wake-up from SLEEP	
	PWRTE = 0	PWRTE = 1	brown-out neset		
XT, HS, LP	72 ms + 1024 Tosc	1024 Tosc	72 ms + 1024 Tosc	1024 Tosc	
RC	72 ms	—	72 ms	—	

TABLE 10-3: TIME-OUT IN VARIOUS SITUATIONS

POR	BOR	то	PD	
0	Х	1	1	Power-on-reset
0	Х	0	Х	Illegal, TO is set on POR
0	Х	Х	0	Illegal, PD is set on POR

Brown-out Reset

WDT Wake-up

MCLR reset during normal operation

MCLR reset during SLEEP

TABLE 10-4: STATUS/PCON BITS AND THEIR SIGNIFICANCE

Х

u

0

u

Ο

Legend: x = unknown, u = unchanged

0

1

1

1

1

Х

0

0

u

1

1

1

1

1

1

NOP	No Operation						
Syntax:	[label]	NOP					
Operands:	None						
Operation:	No opera	tion					
Status Affected:	None						
Encoding:	0 0	0000	0xx0	0000			
Description:	No operati	ion.					
Words:	1						
Cycles:	1						
Example	NOP						

RETFIE	Return from Interrupt						
Syntax:	[label] RETFIE						
Operands:	None						
Operation:	$\begin{array}{l} TOS \to PC, \\ 1 \to GIE \end{array}$						
Status Affected:	None						
Encoding:	00 0000 0000 1001						
Description:	Return from Interrupt. Stack is POPed and Top of Stack (TOS) is loaded in the PC. Interrupts are enabled by setting Global Interrupt Enable bit, GIE (INTCON<7>). This is a two-cycle instruction						
Words:	1						
Cycles:	2						
Example	RETFIE						
	After Interrupt PC = TOS GIE = 1						

OPTION	Load Option Register
Syntax:	[label] OPTION
Operands:	None
Operation:	$(W) \rightarrow OPTION$
Status Affected:	None
Encoding:	00 0000 0110 0010
Description: Words:	The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.
Cycles: Example	1
	To maintain upward compatibility with future PIC [®] MCU products, do not use this instruction.

RETLW	Return with Literal in W				
Syntax:	[<i>label</i>] RETLW k				
Operands:	$0 \le k \le 255$				
Operation:	$k \rightarrow (W);$ TOS \rightarrow PC				
Status Affected:	None				
Encoding:	11 01xx kkkk kkkk				
Description:	The W register is loaded with the eight bit literal 'k'. The program counter is loaded from the top of the stack (the return address). This is a two-cycle instruction.				
Words:	1				
Cycles:	2				
Example	CALL TABLE ;W contains table ;offset value ;W now has table value				
TABLE	ADDWF PC ;W = offset RETLW k1 ;Begin table RETLW k2 ; • RETLW kn ; End of table				
	Before Instruction				
	W = 0x07 After Instruction				
	W = value of k8				

PIC16CE62X

RETURN	Return from Subroutine	RRF	Rotate Right f through Carry			
Syntax:	[label] RETURN	Syntax:	[<i>label</i>] RRF f,d			
Operands:	None	Operands:	$0 \leq f \leq 127$			
Operation:	$TOS \rightarrow PC$		$d \in [0,1]$			
Status Affected:	None	Operation:	See description below			
Encoding:	00 0000 0000 1000	Status Affected:	С			
Description:	Return from subroutine. The stack is	Encoding:	00 1100 dfff ffff			
Words:	POPed and the top of the stack (TOS) is loaded into the program counter. This is a two cycle instruction. 1	Description:	The contents of register 'f' are rotated one bit to the right through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is			
Cycles:	2					
Example	RETURN					
	After Interrupt	Words:	1			
	PC = TOS	Cycles:	1			
		Example	RRF REG1,0			
			Before Instruction			
			REG1 = 1110 0110 C = 0			
			After Instruction			
			$\begin{array}{rcl} \mathbf{REG1} &=& 1110 & 0110 \\ \mathbf{W} &=& 0111 & 0011 \end{array}$			
			C = 0			

RLF	Rotate I	_eft f thr	ough	Carr	у		
Syntax:	[label]	RLF	f,d				
Operands:	$0 \le f \le 1$ $d \in [0,1]$	27					
Operation:	See des	cription I	oelow				
Status Affected:	С						
Encoding:	00	1101	dff	f	ffff		
	one bit to Flag. If 'd the W reg stored ba	one bit to the left through the Carry Flag. If 'd' is 0, the result is placed in the W register. If 'd' is 1, the result is stored back in register 'f'.					
Words:	1						
Cycles:	1						
Example	RLF	RE	G1,0				
	Before II	nstructio	n				
		REG1	=	1110	0110		
	After Inc	C	=	0			
	Alterins	Infraction					
		DEC1		1110	0110		
		REG1 W	= :	1110	0110		

SLEEP

Syntax:	[label]	SLEEP)			
Operands:	None					
Operation:	$\begin{array}{l} 00h \rightarrow WDT, \\ 0 \rightarrow WDT \ \text{prescaler}, \\ 1 \rightarrow \overline{TO}, \\ 0 \rightarrow \overline{PD} \end{array}$					
Status Affected:	TO, PD					
Encoding:	0 0	0000	0110	0011		
Description:	The power-down status bit, PD is cleared. Time-out status bit, TO is set. Watchdog Timer and its prescaler are cleared. The processor is put into SLEEP mode with the oscillator stopped. See Section 10.8 for more details					
Words:	1					
Cycles:	1					
Example:	SLEEP					

SUBLW	Subtract W from Literal	SUBWF	Subtract W from f
Syntax:	[<i>label</i>] SUBLW k	Syntax:	[<i>label</i>] SUBWF f,d
Operands:	$0 \le k \le 255$	Operands:	$0 \le f \le 127$
Operation:	$k - (W) \rightarrow (W)$		d ∈ [0,1]
Status Affected:	C, DC, Z	Operation: Status	(f) - (W) \rightarrow (dest) C, DC, Z
Encoding:	11 110x kkkk kkkk	Affected:	
Description:	The W register is subtracted (2's com- plement method) from the eight bit literal 'k'. The result is placed in the W register.	Encoding: Description:	00 0010 dfff ffff Subtract (2's complement method) W register from register 'f'. If 'd' is 0, the
Words:	1		result is stored in the W register. If 'd' is 1,
Cycles:	1	Words [.]	1
Example 1:	SUBLW 0x02	Cycles:	1
	Before Instruction	Example 1	SUBWE REG1 1
	W = 1 $C = ?$		Before Instruction
	After Instruction W = 1 C = 1; result is positive		REG1 = 3 W = 2 C = ?
Example 2:	Before Instruction		After Instruction
	W = 2 C = ?		REG1 = 1 W = 2 C = 1; result is positive
	After Instruction	Example 2:	Before Instruction
Example 3:	W = 0 C = 1; result is zero Before Instruction		REG1 = 2 W = 2 C = ?
	W = 3		After Instruction
	C = ? After Instruction		REG1 = 0 W = 2 C = 1; result is zero
	VV = 0XFF C = 0; result is nega-	Example 3:	Before Instruction
	tive		REG1 = 1 W = 2 C = ?
			After Instruction
			REG1 = 0xFF W = 2 C = 0; result is negative

12.0 DEVELOPMENT SUPPORT

The PIC[®] microcontrollers are supported with a full range of hardware and software development tools:

- Integrated Development Environment
 - MPLAB[®] IDE Software
- Assemblers/Compilers/Linkers
 - MPASM Assembler
 - MPLAB-C17 and MPLAB-C18 C Compilers
 - MPLINK/MPLIB Linker/Librarian
- Simulators
 - MPLAB-SIM Software Simulator
- Emulators
 - MPLAB-ICE Real-Time In-Circuit Emulator
 - PICMASTER[®]/PICMASTER-CE In-Circuit Emulator
 - ICEPIC™
- In-Circuit Debugger
 - MPLAB-ICD for PIC16F877
- Device Programmers
 - PRO MATE[®] II Universal Programmer
 - PICSTART[®] Plus Entry-Level Prototype Programmer
- Low-Cost Demonstration Boards
 - SIMICE
 - PICDEM-1
 - PICDEM-2
 - PICDEM-3
 - PICDEM-17
 - SEEVAL®
 - KEELOQ[®]

12.1 <u>MPLAB Integrated Development</u> <u>Environment Software</u>

The MPLAB IDE software brings an ease of software development previously unseen in the 8-bit microcontroller market. MPLAB is a Windows[®]-based application which contains:

- · Multiple functionality
 - editor
 - simulator
 - programmer (sold separately)
 - emulator (sold separately)
- A full featured editor
- A project manager
- Customizable tool bar and key mapping
- · A status bar
- On-line help

MPLAB allows you to:

- Edit your source files (either assembly or 'C')
- One touch assemble (or compile) and download to PIC MCU tools (automatically updates all project information)
- Debug using:
 - source files
 - absolute listing file
 - object code

The ability to use MPLAB with Microchip's simulator, MPLAB-SIM, allows a consistent platform and the ability to easily switch from the cost-effective simulator to the full featured emulator with minimal retraining.

12.2 MPASM Assembler

MPASM is a full featured universal macro assembler for all PIC MCUs. It can produce absolute code directly in the form of HEX files for device programmers, or it can generate relocatable objects for MPLINK.

MPASM has a command line interface and a Windows shell and can be used as a standalone application on a Windows 3.x or greater system. MPASM generates relocatable object files, Intel standard HEX files, MAP files to detail memory usage and symbol reference, an absolute LST file which contains source lines and generated machine code, and a COD file for MPLAB debugging.

MPASM features include:

- MPASM and MPLINK are integrated into MPLAB projects.
- MPASM allows user defined macros to be created for streamlined assembly.
- MPASM allows conditional assembly for multi purpose source files.
- MPASM directives allow complete control over the assembly process.

12.3 <u>MPLAB-C17 and MPLAB-C18</u> <u>C Compilers</u>

The MPLAB-C17 and MPLAB-C18 Code Development Systems are complete ANSI 'C' compilers and integrated development environments for Microchip's PIC17CXXX and PIC18CXXX family of microcontrollers, respectively. These compilers provide powerful integration capabilities and ease of use not found with other compilers.

For easier source level debugging, the compilers provide symbol information that is compatible with the MPLAB IDE memory display.

12.4 MPLINK/MPLIB Linker/Librarian

MPLINK is a relocatable linker for MPASM and MPLAB-C17 and MPLAB-C18. It can link relocatable objects from assembly or C source files along with precompiled libraries using directives from a linker script.

13.5 <u>Timing Diagrams and Specifications</u>



FIGURE 13-5: EXTERNAL CLOCK TIMING

TABLE 13-3: EXTERNAL CLOCK TIMING REQUIREMENTS

Parameter No.	Sym	Characteristic	Min	Тур†	Max	Units	Conditions
1A	Fosc	External CLKIN Frequency	DC	_	4	MHz	XT and RC osc mode, VDD=5.0V
		(Note 1)	DC	_	20	MHz	HS osc mode
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency	DC	_	4	MHz	RC osc mode, VDD=5.0V
		(Note 1)	0.1	—	4	MHz	XT osc mode
			1	—	20	MHz	HS osc mode
			DC	-	200	kHz	LP osc mode
1	Tosc	External CLKIN Period	250	—	—	ns	XT and RC osc mode
		(Note 1)	50	—	—	ns	HS osc mode
			5	—	—	μs	LP osc mode
		Oscillator Period	250	_	—	ns	RC osc mode
		(Note 1)	250	—	10,000	ns	XT osc mode
			50	—	1,000	ns	HS osc mode
			5	—	—	μs	LP osc mode
2	TCY	Instruction Cycle Time (Note 1)	200	_	DC	ns	Tcy=Fosc/4
3*	TosL,	External Clock in (OSC1) High or	100*	_	_	ns	XT oscillator, Tosc L/H duty cycle
	TosH	Low Time	2*	—	—	μs	LP oscillator, Tosc L/H duty cycle
			20*	—	—	ns	HS oscillator, Tosc L/H duty cycle
4*	TosR,	External Clock in (OSC1) Rise or	25*	_	_	ns	XT oscillator
	TosF	Fall Time	50*	—	—	ns	LP oscillator
			15*	—	—	ns	HS oscillator

These parameters are characterized but not tested.

† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time-base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1 pin. When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

18-Lead Plastic Dual In-line (P) – 300 mil (PDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





	Units		INCHES* MILLIMETERS				6
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	р		.100			2.54	
Top to Seating Plane	Α	.140	.155	.170	3.56	3.94	4.32
Molded Package Thickness	A2	.115	.130	.145	2.92	3.30	3.68
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	Е	.300	.313	.325	7.62	7.94	8.26
Molded Package Width	E1	.240	.250	.260	6.10	6.35	6.60
Overall Length	D	.890	.898	.905	22.61	22.80	22.99
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.045	.058	.070	1.14	1.46	1.78
Lower Lead Width	В	.014	.018	.022	0.36	0.46	0.56
Overall Row Spacing	eВ	.310	.370	.430	7.87	9.40	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

*Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-001

Drawing No. C04-007

14.1 Package Marking Information

18-Lead PDIP



20-Lead SSOP



Example



Example



Example



Example



Legend	: XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	In the even be carried characters	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available of or customer-specific information.

PIC16CE62X

INDEX

Α	
ADDLW Instruction	
ADDWF Instruction	
ANDLW Instruction	
ANDWF Instruction	
Architectural Overview	7
Assembler	
MPASM Assembler	77
в	

В

BCF Instruction	
Block Diagram	
TIMER0	35
TMR0/WDT PRESCALER	
Brown-Out Detect (BOD)	
BSF Instruction	68
BTFSC Instruction	
BTFSS Instruction	
С	

CALL Instruction	
Clocking Scheme/Instruction Cycle	10
CLRF Instruction	69
CLRW Instruction	69
CLRWDT Instruction	70
CMCON Register	
Code Protection	64
COMF Instruction	
Comparator Configuration	42
Comparator Interrupts	
Comparator Module	41
Comparator Operation	
Comparator Reference	
Configuration Bits	50
Configuring the Voltage Reference	47
Crystal Operation	51
_	

D

Data Memory Organization	12
DECF Instruction	70
DECFSZ Instruction	70
Development Support	77
E	

Е

EEPROM Peripheral Operation	29
Errata	2
External Crystal Oscillator Circuit	52

G

General purpose Register File	12
GOTO Instruction	71

L

I/O Ports	23
I/O Programming Considerations	
ID Locations	64
INCF Instruction	71
INCFSZ Instruction	71
In-Circuit Serial Programming	64
Indirect Addressing, INDF and FSR Registers	21
Instruction Flow/Pipelining	10
Instruction Set	
ADDLW	67
ADDWF	67
ANDLW	67
ANDWF	67
BCF	68
BSF	
-	

BTFSC	68
BTFSS	69
CALL	69
	69
	09 70
COMF	70
DECF	70
DECFSZ	70
GOTO	71
	71
	/1 71
IORWE	72
MOVF	72
MOVLW	72
MOVWF	72
NOP	73
OPTION	73
	73
BETURN	73
RLF	74
RRF	74
SLEEP	74
SUBLW	75
SUBWF	75
TRIS	76
	76
XORLW	76
XORUW	76 65
XORLW XORWF	76 65 60
XORUW XORWF Instruction Set Summary INT Interrupt INTCON Register	76 65 60 17
XORUWXORWF Instruction Set Summary INT Interrupt INTCON Register Interrupts	76 65 60 17 59 71
XORLW XORWF Instruction Set Summary INT Interrupt INTCON Register. Interrupts IORLW Instruction IORWF Instruction	76 65 60 17 59 71 72
XORUF	76 65 60 17 59 71 72
XORWF	76 65 60 17 59 71 72 80
XORWF	76 65 60 17 59 71 72 80
XORWF	76 65 60 17 59 71 72 80
XORWF	76 65 60 17 59 71 72 80 72 72
XORWF	 76 65 60 17 59 71 72 80 72 74 74 74 75 75 76 <
XORWF	76 65 60 17 59 71 72 80 72 72 72 72 72
XORUF XORWF Instruction Set Summary INT Interrupt INTCON Register Interrupts IORLW Instruction IORWF Instruction IORWF Instruction K KeeLoq® Evaluation and Programming Tools M MOVF Instruction MOVLW Instruction MOVLW Instruction MOVLW Instruction MOVLW Instruction MOVWF Instruction MOVWF Instruction MOVWF Instruction MOVWF Instruction MOVWF Instruction MOVWF Instruction MOVWF Instruction MOVAB Integrated Development Environment Software N	76 65 60 17 59 71 72 80 72 72 72 77
XORUFXORWF	76 65 60 17 59 71 72 80 72 72 72 72 77 73
XORUFXORWF Instruction Set Summary INT Interrupt INTCON Register INTCON	76 65 60 17 59 71 72 80 72 72 72 77 73
XORWF	76 65 60 17 59 71 72 80 72 72 77 73 . 5
XORWF	76 65 60 17 59 71 72 80 72 72 72 77 73 . 5 73
XORUF	76 65 60 17 59 71 72 80 72 72 72 77 73 . 5 73 16
XORUF	76 65 60 17 59 71 80 72 72 73 .5 73 .5 73 .5 73 .5 73 .5 .5
XORWF	76 65 60 17 59 71 72 80 72 77 73 .5 73 .5 51 54
XORWF	76 65 60 17 59 71 72 80 72 72 77 73 . 5 73 16 51 54
XORUFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWFXORWF INSTRUCTIONXORWF InstructionXORVF INSTRUCTIONX	76 60 65 60 17 59 71 72 80 722 77 73 . 53 16 51 54 01 54
XORUF	76 660 17 59 71 72 80 7272 77 73 .53 16 51 54 01 97 20
XORUFXORWF .	76 660 17 59 72 72 77 73 .53 16 54 01 97 20 197 20
XORUFXORWF INSTRUCTIONXORWF INSTRUCTIONXORVF INSTRUCTIONYORVF INSTRUCTIONYORV	76 60 60 179 70 77 70 77 71 73 73 73 73 16 16 15 17 10 10 10 10 10 10 10 11 10 12 10 13 10 14 10 15 10 16 10 17 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10 10
XORWF	76560175972 80727277 73.5736151 9720197979

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